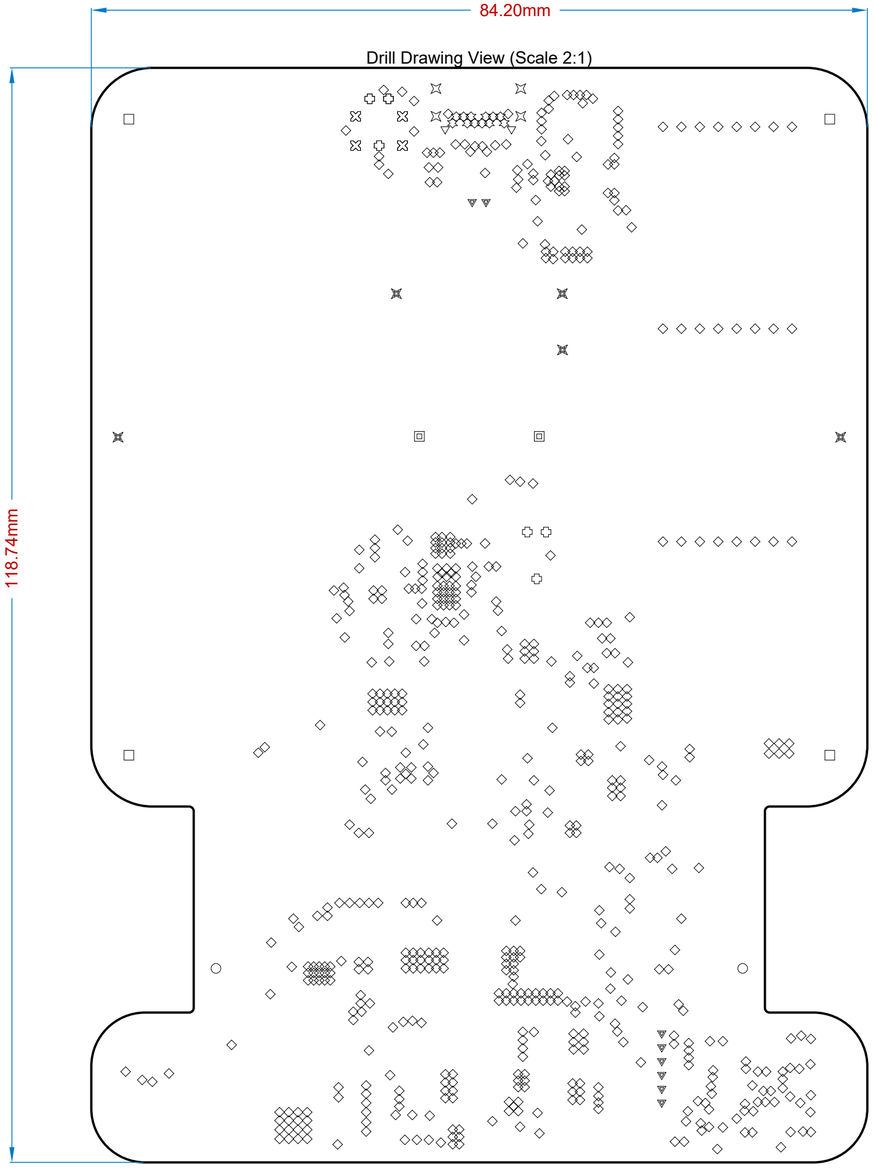


Drill Drawing View (Scale 2:1)

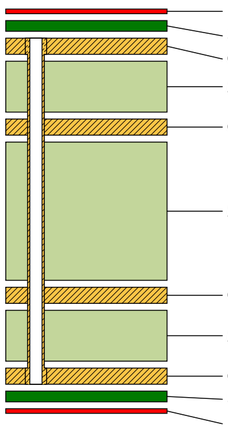
NOTE: (UNLESS OTHERWISE SPECIFIED)

1. VERIFY ARTWORK TO SUPPLIED IPC-356 NETLIST.
2. PRINTED CIRCUIT BOARD (PCB) TO BE FABRICATED IN ACCORDANCE WITH IPC-600A, CLASS 2 LATEST REVISION.
3. MATERIAL TO BE FR4 GLASS EPOXY LAMINATE IN ACCORDANCE WITH IPC-4101/24. FR4 170Tg, OR RoHS EQUIVALENT.
4. APPLY SOLDERMASK OVER BARE COPPER IN ACCORDANCE WITH IPC-SM-840, LATEST REVISION, BOTH SIDES, LIQUID-PHOTO IMAGEABLE (LPI) COLOR GREEN.
5. SILKSCREEN ACCORDING TO SUPPLIED ARTWORK USING PERMANENT, WHITE, NON-CONDUCTIVE, EPOXY BASED INK. LANDS AND EXPOSED PLATED AREAS TO BE FREE OF INK.
6. FINISH: ENIG (ELECTROLESS NICKEL IMMERSION GOLD)
7. MARK ALL BOARDS WITH EITHER, CAGE CODE, DATE CODE, AND/OR UL RATING ON SOLDER SIDE USING SILKSCREEN OR ETCH.
8. BOARDS TO BE 100% TESTED FOR CONTINUITY AND ISOLATION.
9. PLATED THROUGH HOLE DIMENSIONS APPLY AFTER PLATING, FISINHED HOLE SIZE (FHS).
10. ALL PLATED THROUGH HOLES TO HAVE MINIMUM OF 0.001" PLATED COPPER.
11. ALL HOLES TO BE LOCATED WITHIN 0.003" DIAMETER FROM TRUE POSITION; LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
12. CONDUCTOR WIDTHS AND SPACING SHALL BE BETWEEN +/- 20% OF SUPPLIED ARTWORK.
13. MAXIMUM BOW AND TWIST NOT TO EXCEED 0.0075" PER INCH.
14. BOARDS TO MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0 OR BETTER.
15. FINISHED BOARD THICKNESS IS INDICATED IN THE PCB CROSS-SECTIONAL DIAGRAM.
16. COPPER WEIGHTS SHOWN IN PCB CROSS-SECTIONAL DIAGRAM INDICATE WEIGHTS AFTER PLATING.
17. VENDOR MAY NOT MODIFY MASTER GERBER DATA WITHOUT AUTHORIZATION, EXCEPT BELOW:
    A. NON-FUNCTIONAL PADS MAY BE REMOVED FROM INTERNAL SIGNAL LAYERS AS NEEDED.
    B. TEARDROPS/PAD FILLETS MAY BE ADDED AS NEEDED TO MAINTAIN ANNULAR RING AT THE CONDUCTOR-TO-PAD CONNECTION POINT.
18. ASSEMBLY PROCESS IS RoHS, BASE LAMINATE MUST BE RoHS COMPLIANT.
19. DIFF PAIRS: 90 OHM DIFF PAIRS +/- 10% ON LAYERS 1 & 4 WITH .127mm ETCH, 0.127mm SPACING.

Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Hole Tolerance	Hole Length
◇	616	0.3048mm	Plated	Round	+0.0762mm/-0.3048mm	
✡	12	0.4000mm	Plated	Round	+/-0.0500mm	
⌑	4	0.6000mm	Plated	Slot	+/-0.0500mm	1.6000mm
▽	8	0.7000mm	Plated	Round	+/-0.0762mm	
▽	2	0.7500mm	Non-Plated	(Mixed)	+/-0.0762mm	(Mixed)
⌖	9	0.9906mm	Non-Plated	Round	+/-0.0762mm	
⊠	8	2.3749mm	Non-Plated	Round	+/-0.0762mm	
○	2	3.0480mm	Non-Plated	Round	+/-0.0762mm	
□	4	3.1750mm	Non-Plated	Round	+/-0.0762mm	
⌘	5	4.0000mm	Plated	Round	+/-0.0762mm	
⧈	2	5.0800mm	Non-Plated	Round	+/-0.0762mm	
	672 Total					

Layer Stack Legend



Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Silk Screen			Legend	GTO
Surface Material	Top Solder Mask	0.0232mm	SM-003	Solder Mask	GTS
CF-004	Top Layer	0.0350mm		Signal	GTL
Prepreg		*0.1104mm*	*PP-023*	*Dielectric*	
CF-004	Layer 2	0.0350mm		Signal	G1
Prepreg		*1.1676mm*	*PP-023*	*Dielectric*	
CF-004	Layer 3	0.0350mm		Signal	G2
Prepreg		*0.1104mm*	*PP-023*	*Dielectric*	
CF-004	Bottom Layer	0.0350mm		Signal	GBL
Surface Material	Bottom Solder Mask	0.0232mm	SM-003	Solder Mask	GBS
	Bottom Silk Screen			Legend	GBO

Total thickness: 1.5748mm

PCB THICKNESS = 1.575mm / 62 mils. All layers are 1oz cu.

DIELECTRIC MATERIAL AND THICKNESS TO BE DETERMINED BY FABRICATION HOUSE.

TAB.REV.	TAB.NO.

REV	ECO	DATE	APP

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.

TOLERANCES ARE:
DECIMALS:
.XX +/- .01
.XXX +/- .005
FRACTIONS:
+/- 1/64
ANGLES:
+/- 1 O

DO NOT SCALE DWG.

SCALE 1:1

DRAWN	NET RESULTS	10/03/24
CHECKED		
ENGINEER		

NOTICE

ODIC, INC.
295 FOSTER ST. SUITE 202 LITTLETON, MA 01460

TITLE:

GHL NAATOS SAMPLE PREP MAIN BOARD

FABRICATION DRAWING

SIZE	PART NO.	DOCUMENT REVISION
C	263-03-001	B